

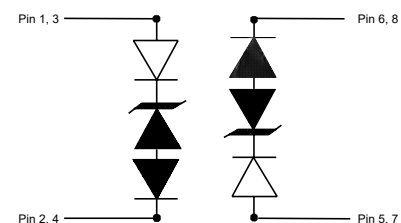
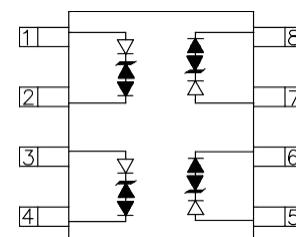


## Discription

The HSLVU2.84BTG protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.



SOP-8  
(SOIC-8)



Circuit Diagram

## Features

- 400W peak pulse power (8/20 $\mu$ s)
- Protects two line pairs (four lines)
- Ultra low leakage: nA level
- Low operating voltage: 2.8V
- Very low capacitance: 2pF
- Ultra low clamping voltage
- JEDEC SO-8 package
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    - Air discharge:  $\pm 30$ kV
    - Contact discharge:  $\pm 30$ kV
  - IEC61000-4-5 (Lightning) 30A (8/20 $\mu$ s)
- RoHS Compliant

## Ordering information

Product ID	Pack	Qty(PCS)
HSLVU2.84BTG	SOP-8(SOIC-8)	2500

## Absolute Ratings ( $T_{amb}=25^{\circ}\text{C}$ )

Symbol	Parameter	Value	Units
$P_{PP}$	Peak Pulse Power ( $t_p = 8/20\mu\text{s}$ )	400	W
$T_L$	Maximum lead temperature for soldering during 10s	260	$^{\circ}\text{C}$
$T_{stg}$	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
$T_{op}$	Operating Temperature Range	-40 to +125	$^{\circ}\text{C}$
$T_j$	Maximum junction temperature	150	$^{\circ}\text{C}$
	IEC61000-4-2 (ESD)	air discharge contact discharge	$\pm 30$ $\pm 30$ KV

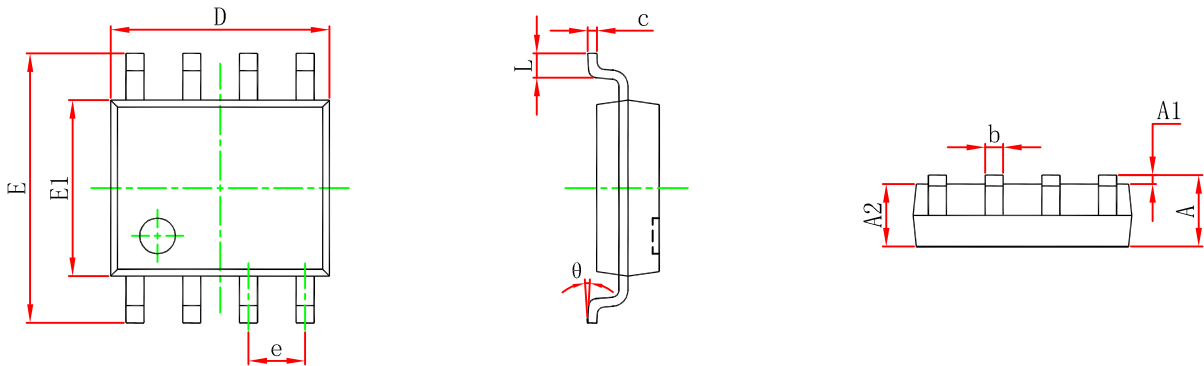


**Electrical Characteristics ( $T_A=25^{\circ}\text{C}$  unless otherwise specified)**

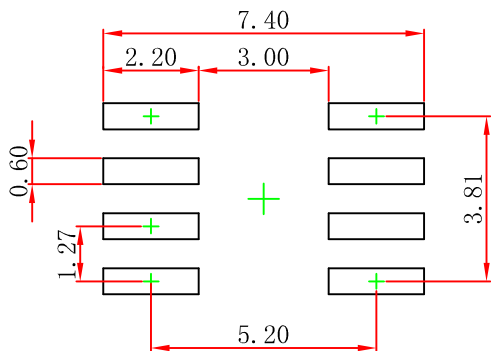
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			2.8	V	
Breakdown Voltage	VBR	3.0			V	$I_T = 2\mu\text{A}$
	VS <sub>B</sub>	3.0			V	$I_{SB} = 50\text{mA}$
Reverse Leakage Current	I <sub>R</sub>		0.001	1	$\mu\text{A}$	$V_{RWM} = 2.8\text{V}$
Clamping Voltage	V <sub>C</sub>			8.5	V	$I_{PP} = 5\text{A}$ (8 x 20 $\mu\text{s}$ pulse)
Clamping Voltage	V <sub>C</sub>			18	V	$I_{PP} = 20\text{A}$ (8 x 20 $\mu\text{s}$ pulse)
Junction Capacitance	C <sub>J</sub>		2	3	pF	$V_R = 0\text{V}$ , $f = 1\text{MHz}$



SOP-8(SOIC-8) Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Note:  
1.Controlling dimension:in millimeters.  
2.General tolerance:± 0.05mm.  
3.The pad layout is for reference purposes only.



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